

MSC2X51/50SDA170J Dual Silicon Carbide Schottky Barrier Diodes

Product Overview

The silicon carbide (SiC) power Schottky barrier diode (SBD) product line from Microsemi increases the performance over silicon diode solutions while lowering the total cost of ownership for high-voltage applications. MSC2X51/50SDA170J are dual 1700 V, 50 A SiC SBD devices in a SOT-227 package.

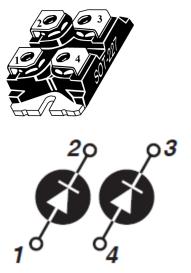


Figure 1 • Parallel MSC2X51SDA170J

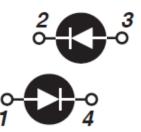


Figure 2 • Anti-parallel MSC2X50SDA170J

Features

The following are key features of the MSC2X51SDA170J and MSC2X50SDA170J devices:

- No reverse recovery
- Low forward voltage
- Low leakage current
- Avalanche-energy rated
- RoHS compliant
- Isolated voltage to 2500 V

Benefits

The following are benefits of the MSC2X51SDA170J and MSC2X50SDA170J devices:

- Outstanding performance at high-frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction-to-case thermal resistance
- RoHS compliant



Applications

The MSC2X51SDA170J and MSC2X50SDA170J devices are designed for the following applications:

- Power factor correction (PFC)
- Anti-parallel diode
 - Switch-mode power supply
 - Inverters/converters
 - Motor controllers
- Freewheeling diode
 - Switch-mode power supply
 - Inverters/converters
- Snubber/clamp diode



Device Specifications

This section shows the specifications of the MSC2X51SDA170J and MSC2X50SDA170J devices.

Absolute Maximum Ratings

The following table shows the absolute maximum ratings per diode of the MSC2X51SDA170J and MSC2X50SDA170J devices. $T_c = 25$ °C unless otherwise specified.

Table 1 • Absolute Maximum Ratings

Symbol	Parameter		Ratings	Unit
V _R	Maximum DC reverse voltage		1700	v
I _F	Maximum DC forward current	T _C = 115 °C	50	A

The following table shows the thermal and mechanical characteristics of the MSC2X51SDA170J and MSC2X50SDA170J devices.

Symbol	Characteristics	Min	Тур	Max	Unit
R _{OJC}	Junction-to-case thermal resistance		0.35	0.50	°C/W
VISOLATION	RMS voltage (50 Hz–60 Hz sinusoidal waveform from terminals to mounting base for 1 minute)	2500			V
T _J , T _{STG}	Operating junction and storage tempera- ture range	-55		175	°C
Wt	Package weight		1.03		oz
			29.2		g
	Mounting torque, M4 screw		10		lbf-in
			1.1		N.m

Table 2 • Thermal and Mechanical Characteristics



Electrical Performance

The following table shows the static characteristics per diode of the MSC2X51SDA170J and MSC2X50SDA170J devices. T_J = 25 °C, unless otherwise specified.

Table 3 • Static Characteristics Per Diode

Symbol	Characteristics	Test Conditions		Min	Тур	Max	Unit
V _F	Diode forward voltage	I _F = 50 A	T _J = 25 °C		1.5	1.8	V
			T _J = 175 °C		2.0		
I _{RM}	Reverse leakage current	V _R = 1700 V	T _J = 25 °C		50	200	μΑ
			T _J = 175 °C		250		
Q _C	Total capacitive charge	V _R = 900 V			410		nC
Cj	Junction capacitance	V _R = 600 V, f = 1 MHz V _R = 900 V, f = 1 MHz		30	300		pF
					250		



Typical Performance Curves

This section shows the typical performance curves per diode of the MSC2X51SDA170J and MSC2X50SDA170J devices.

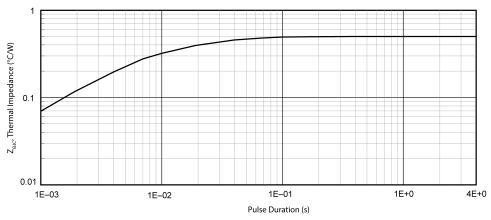
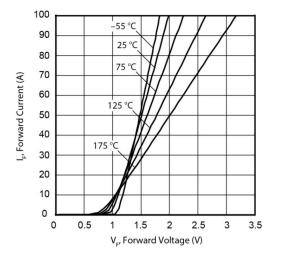


Figure 3 • Maximum Transient Thermal Impedance



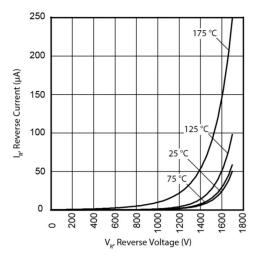


Figure 4 • Forward Current vs. Forward Voltage

Figure 5 • Reverse Current vs. Reverse Voltage



Package Specification

This section shows the package specification of the MSC2X51SDA170J and MSC2X50SDA170J devices.

Package Outline Drawing

The following figure illustrates the SOT-227 package outline of the MSC2X51SDA170J and MSC2X50SDA170J devices. The dimensions in the figure below are in millimeters and (inches).

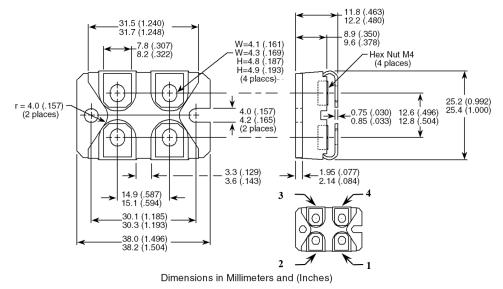


Figure 6 • Package Outline Drawing





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